

AA2214SURSK-AMT

2.2 x 1.4 mm Surface Mount LED Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AIGaInP on GaAs substrate Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 2.2 mm x 1.4 mm, 1.3 mm high
- Low power consumption
- · Available on tape and reel
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- RoHS compliant

APPLICATIONS

- Traffic signaling
- · Backlighting (illuminated advertising, general lighting)
- · Interior and exterior automotive lighting
- Substitution of micro incandescent lamps
- Reading lamps
- Signal and symbol luminaire for orientation
- Marker lights (e.g. Steps, exit ways, etc)
- · Decorative and entertainment lighting
- Indoor and outdoor commercial and residential architectural lighting

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices



- Notes 1. All dimensions are in millimeters (inches).

RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)

Tolerance is ±0.2(0.008") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to

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change without prior notice. The device has a single mounting surface. The device must be mounted according to the specifications.

0.8

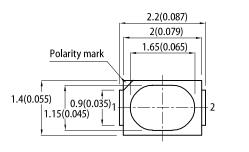
SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA ^[2]			Viewing Angle [1]	
			Code.	Min.	Max.	201/2	
AA2214SURSK-AMT			Р	200	300		
			Q	300	400		
	Liver Ded (AlColpD)	Watan Class	R	400	500	120°	
	Hyper Red (AlGaInP)	Water Clear	*H	*55	*80		
			*M	*80	*120		
			*N	*120	*200		

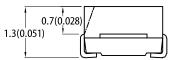
Notes

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
- * Luminous intensity value is traceable to CIE127-2007 standards.

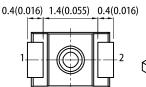
PACKAGE DIMENSIONS



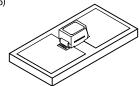




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1.2



Solder Resist

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ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Current of Carrithing Color	Emitting Color	Value			11-14
Parameter	Symbol	Emitting Color	Min.	Тур.	Max.	Unit
Wavelength at Peak Emission I_F = 20mA	λ_{peak}	Hyper Red	-	645	-	nm
Dominant Wavelength I _F = 20mA	λ_{dom} ^[1]	Hyper Red	620	-	640	nm
Spectral Bandwidth at 50% Φ REL MAX I_F = 20mA	Δλ	Hyper Red	-	28	-	nm
Capacitance	С	Hyper Red	-	35	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red	-	1.95	2.5	V
Reverse Current (V _R = 5V)	I _R	Hyper Red	-	-	10	uA
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C $\leq T \leq$ 100°C	TC _{λpeak}	Hyper Red	-	0.13	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10 $^{\circ}C \leq T \leq$ 100 $^{\circ}C$	TC _{λdom}	Hyper Red	-	0.05	-	nm/°C
Temperature Coefficient of $~V_F$ I_F = 20mA, -10°C \leq T \leq 100°C	TCv	Hyper Red	-	-1.9	-	mV/°C

Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.) 2. Forward voltage: ±0.1V.

Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Symbol Value Parameter P_D 75 **Power Dissipation** V_{R} 5 **Reverse Voltage** Junction Temperature Ti 115 **Operating Temperature** T_{op} -40 to +100 Storage Temperature T_{stg} -40 to +115 DC Forward Current 30 \mathbf{I}_{F} $I_{FM}^{[1]}$ 185 Peak Forward Current Electrostatic Discharge Threshold (HBM) 3000 - $R_{th\;JA}\;^{[2]}$ 405 Thermal Resistance (Junction / Ambient) $R_{th\ JS}$ [2] Thermal Resistance (Junction / Solder point) 260

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Notes

Unit

mW

V

°C

°C

°C

mΑ

mΑ

V

°C/W

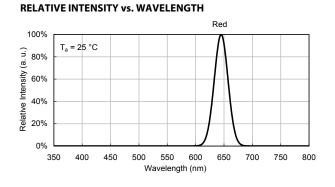
°C/W

noiss. 1. /1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th JA} ,R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

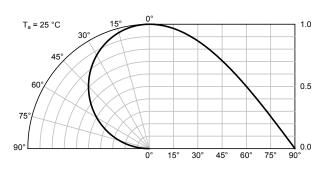
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AA2214SURSK-AMT

TECHNICAL DATA



SPATIAL DISTRIBUTION



HYPER RED

50

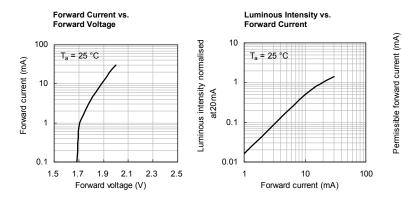
40

30 20

10

0

-40

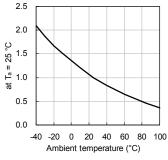


Ambient temperature (°C)

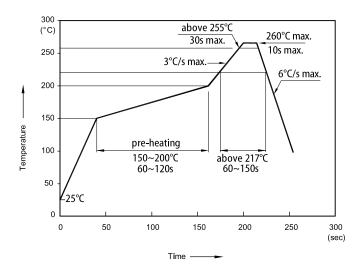
-20 0 20 40 60 80 100

Forward Current Derating Curve

Luminous Intensity vs. Ambient Temperature



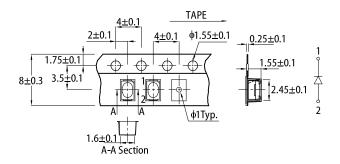
REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



Notes.

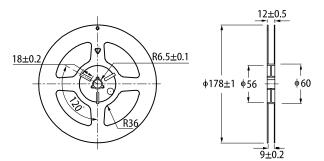
- Don't cause stress to the LEDs while it is exposed to high temperature.
 The maximum number of reflow soldering passes is 2 times.
 Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

TAPE SPECIFICATIONS (units : mm)



-uminous intensity normalised

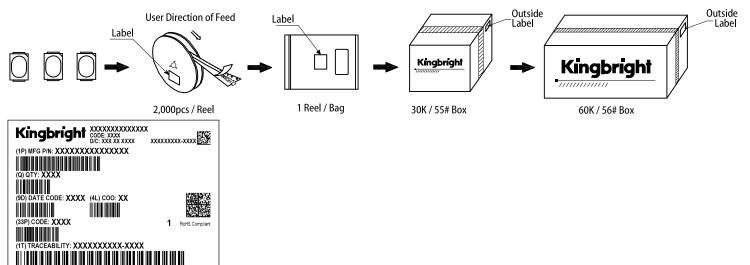
REEL DIMENSION (units : mm)



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PACKING & LABEL SPECIFICATIONS



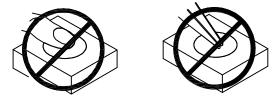
HANDLING PRECAUTIONS

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



- 4-1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4-2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4-3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
- As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of lead frame. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

 Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.





RELIABILITY TEST ITEMS AND CONDITIONS

The reliability of products shall be satisfied with items listed below

LOT TOLERANCE PERCENT DEFECTIVE (LTPD): 10%

No.	Test Item	Standards	Test Condition	Test Times / Cycles	Number of Damaged
1	Continuous operating test	-	T_a = 25°C, I _F = maximum rated current *	1,000 h	0 / 22
2	High Temp. operating test	EIAJ ED-4701/100(101)	T_a = 100°C, I _F = derated current at 100°C	1,000 h	0 / 22
3	Low Temp. operating test	-	T_a = -40°C, I _F = maximum rated current *	1,000 h	0 / 22
4	High temp. storage test	EIAJ ED-4701/100(201)	T _a = maximum rated storage temperature	1,000 h	0 / 22
5	Low temp. storage test	EIAJ ED-4701/100(202)	T _a = -40°C	1,000 h	0 / 22
6	High temp. & humidity storage test	-	T _a = 60°C, RH = 90%	500 h	0 / 22
7	High temp. & humidity operating test	-	$T_a = 60^{\circ}C$, RH = 90% I_F = derated current at $60^{\circ}C$	500 h	0 / 22
8	Soldering reliability test	EIAJ ED-4701/100(301)	Moisture soak: 30°C, 70% RH, 72h Preheat: 150~180°C (120s max.) Soldering temp: 260°C(10s)	2 times	0 / 18
9	Thermal shock operating test	-	$T_a = -40^{\circ}C(15min) \sim 100^{\circ}C(15min)$ I _F = derated current at 100°C	1,000 cycles	0 / 22
10	Thermal shock test	-	T _a = -40°C(15min) ~ 100°C(15min)	1,000 cycles	0 / 22
11	Electric Static Discharge (ESD)	EIAJ ED-4701/100(304)	C = 100pF, R2 = 1.5KΩ V = 3000V	Once each Polarity	0 / 22
12	Vibration test	-	a = 196m/s ² , f = 100~2KHz, t = 48min for all xyz axes	4 times	0 / 22

* : Refer to forward current vs. derating curve diagram

CRITERIA FOR JUDGING DAMAGE

Items	Symbols	Conditions	Failure Criteria		
luminous Intensity	Ι _V	I _F = 20mA	Testing Min. Value < Spec. Min. Value x 0.5		
Forward Voltage	V _F	I _F = 20mA	Testing Max. Value ≥ Spec. Max. Value x 1.2		
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage	Testing Max. Value ≥ Spec. Max. Value x 2.5		
High temp. storage test	-	-	Occurrence of notable decoloration, deformation and cracking		

PRECAUTIONARY NOTES

The information included in this document reflects representative usage scenarios and is intended for technical reference only.

The part number determine decline in this document in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
 When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If

customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.

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